

IN THE CLAIMS:

Please cancel claims 15-17 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claims 1 and 8 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Currently Amended) A planar package structure for high power light emitting diode, comprising:

a substrate;

a package material;

5 a light emitting diode chip ~~disposed on the substrate, in direct contact with the~~
substrate and having a main light emitting surface ~~served as~~ providing a light source;
and

a planar optical modulation unit disposed on the package material, ~~so that the~~
planar optical modulation unit is located above the main light emitting surface and
10 utilized for modulating ~~the~~ an optical phase of the light source.

Claim 2. (Original) The planar package structure for high power light emitting diode of claim 1, wherein the package material is made of transparent resin.

Claim 3. (Original) The planar package structure for high power light emitting diode of claim 1, wherein the package material is made of polymer material.

Claim 4. (Original) The planar package structure for high power light emitting diode of claim 1, wherein the planar optical modulation unit performs a refractive optical phase modulation.

Claim 5. (Original) The planar package structure for high power light emitting diode of claim 1, wherein the planar optical modulation unit performs a diffractive optical phase modulation.

Claim 6. (Original) The planar package structure for high power light emitting diode of claim 1, wherein the planar optical modulation unit is a Fresnel lens structure.

Claim 7. (Original) The planar package structure for high power light emitting diode of claim 1, wherein the planar optical modulation unit is a lens structure with a gradient refractive index.

Claim 8. (Currently Amended) A planar package structure for high power light emitting diode, comprising:

a substrate;

a package material;

a plurality of light emitting diode chips ~~disposed on~~ in direct contact with the substrate, each light emitting diode chip having a main light emitting surface ~~served as~~ providing a light source; and

a plurality of planar optical modulation units disposed on the package material, ~~so that~~ each of the planar optical modulation units is located above each of the main light emitting surface respectively, and utilized for modulating the optical phase of each of the light sources.

Claim 9. (Original) The planar package structure for high power light emitting diode of claim 8, wherein the package material is made of transparent resin.

Claim 10. (Original) The planar package structure for high power light emitting diode of claim 8, wherein the package material is made of polymer material.

Claim 11. (Original) The planar package structure for high power light emitting diode of claim 8, wherein each of the planar optical modulation units performs a refractive optical phase modulation.

Claim 12. (Original) The planar package structure for high power light emitting diode of claim 8, wherein each of the planar optical modulation units performs a diffractive optical phase modulation.

Claim 13. (Original) The planar package structure for high power light emitting diode of claim 8, wherein each of the planar optical modulation units is a Fresnel lens structure.

Claim 14. (Original) The planar package structure for high power light emitting diode of claim 8, wherein each of the planar optical modulation units is a lens structure with a gradient refractive index.

Claims 15-17 (Cancelled)